

Patent Application
Docket No.27889-37

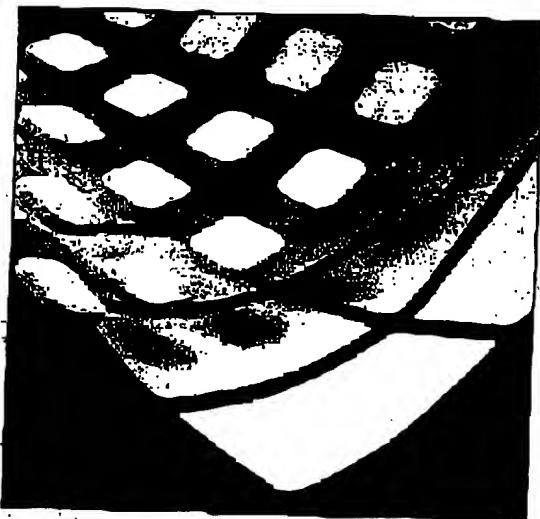
Exhibit A

Advertisements for "thermal interface materials"

1. **W.L. Gore and Associates, Inc.'s POLARCHIP™**
2. **Thermalloy, Inc.'s Thermalcote II**
3. **Stockwell Rubber Company's Thermal Management Components**

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Gore's POLARCHIP™ Thermal Interface Materials... Bridge the Gap Between Hot PCBs and Cool Heat Sinks.



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POLARCHIP Materials are An Ideal "Gap-Filler" for Large or Variable Gaps

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Thermalcote II
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Advanced technology in semiconductor assembly

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Reader Interest Rating

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